

Title (en)  
METHOD FOR BONDING HIGH HEAT CONDUCTIVE INSULATING RESIN

Title (de)  
VERFAHREN ZUR BINDUNG EINES IN HOHEM MASSE WÄRMELEITFÄHIGEN ISOLIERENDEN HARZES

Title (fr)  
PROCÉDÉ DE LIAISON DE RÉSINE ISOLANTE FORTEMENT THERMO-CONDUCTRICE

Publication  
**EP 2434541 A4 20140402 (EN)**

Application  
**EP 09844913 A 20090521**

Priority  
JP 2009059338 W 20090521

Abstract (en)  
[origin: US2011174428A1] Provided is a method for bonding a high heat conductive insulating resin, by which the high heat conductive insulating resin can be bonded to a heat sink without deteriorating insulating characteristics and heat conducting characteristics. The method includes: a fixing step of fixing the heat sink by means of a jig having a vacuuming function; a placing step of placing the heat sink fixed with the jig on a sheet-like high heat conductive insulating resin previously bonded to a cooler and making a hermetically closed space; and a bonding step of having a bonding section between the heat sink and the sheet-like high heat conductive insulating resin under a negative pressure by depressurizing the hermetically closed space, heating the sheet-like high heat conductive insulating resin, and bonding the sheet-like high heat conductive insulating resin to the heat sink.

IPC 8 full level  
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Citation (search report)

- [A] JP 2004087735 A 20040318 - TOSHIBA CORP
- [A] EP 1622437 A1 20060201 - THALES SA [FR]
- [A] US 2009116197 A1 20090507 - FUNAKOSHI SUNAO [JP], et al
- [A] US 6048656 A 20000411 - AKRAM SALMAN [US], et al
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DOCDB simple family (publication)  
**US 2011174428 A1 20110721**; **US 8277597 B2 20121002**; CN 102326251 A 20120118; CN 102326251 B 20140122; EP 2434541 A1 20120328; EP 2434541 A4 20140402; EP 2434541 B1 20150729; JP 5177229 B2 20130403; JP WO2010134180 A1 20121108; WO 2010134180 A1 20101125

DOCDB simple family (application)  
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